



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: B. Kim et al. Attorney Docket No.: SEMT119849
Application No.: 10/700,782 Group Art Unit: 1753
Filed: November 3, 2003 Examiner: Edna Wong
Title: BATH AND METHOD FOR HIGH RATE COPPER DEPOSITION

INFORMATION DISCLOSURE STATEMENT

Seattle, Washington 98101

March 26, 2004

TO THE COMMISSIONER FOR PATENTS:

Applicants are aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

1. X Copies of the listed publications are enclosed for the Examiner's use.
2. X Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

CHRISTENSEN O'CONNOR
JOHNSON KINDNESS^{PLLC}

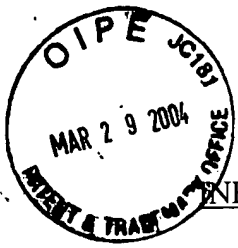
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INFORMATION CITED BY APPLICANTS THAT MAY BE MATERIAL TO THE
PROSECUTION OF THE SUBJECT APPLICATION

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